



THERMAL SHOCK

Manufacturer:	ESPEC
Type/Model:	TSD-100
Interior Volume:	3.5 cu ft / 100 Liters
Interior Dimensions:	28" W x 16" D x 13.5" H
Temperature Range:	-65 to 200 °C / -94 to 392°F
Transfer Rate:	<11 seconds between zones
Cooling Method:	Air Cooled



The thermal shock chamber has the capability of taking a system component and subjecting the part to a rapid thermal shock load. The chamber uses a basket as an elevator that moves a part from one zone to another hot/cold – cold/hot in under 11(s). This can be an important tool when investigating the effects of thermal cycling on system components that encounter various thermal gradients during operation. In electronics this thermal cycling can prove useful in finding components that have solder stress fractures or problems with the components themselves breaking under the temperature cycling.

